

Call for Papers

ADMETA^{Plus} 2017



Advanced Metallization Conference 2017: 27th Asian Session

Oct. 18 - 20, 2017

The University of Tokyo, Yayoi Auditorium, Ichijo Hall (Hongo Campus), Tokyo

Sponsorship by ADMETA Committee

Co-sponsorship by the Japan Society of Applied Physics

The ADMETA^{Plus} has been heading for the 27th historical meeting and long contributed to practical progress for advanced MPU and various memory devices. In recent years, the importance of interconnect technology for realizing low resistance, large integration, rich function, low cost, and high reliability is increasing more and more in various device application fields beyond silicon electronics. This conference is focusing interconnects technology and science related to materials, processes, device design, assembly, equipment, cost performance, and characterization. We will conduct comprehensive discussions widely from basics to applications with researchers and engineers from industry, government, and academia. We are looking forward to newly developing interconnect technology fields and also contributing the growth of semiconductor industry in the Asian area.

ADMETA^{Plus} 2017 General Chair: Osamu Nakatsuka (Nagoya University)

Conference Topics of Interest

Integration: Interconnection Structure and Performance, Parasitic Capacitance, Reliability Technology, Testing and Analysis

Reliability Science and Failure Analysis: EM, SIV, TDDDB, Defect Detection and Analysis, Failure Mechanism and Modeling

Metallization: PVD, CVD, ALD, Plating, Barrier Metal, Seed and Nucleation Layer, Supercritical Fluid, Reflow

Low-k Dielectric: CVD, ALD, SOD, Film Properties, Interface Control, New Materials, Dielectric Structures (Air Gap), Metrology, etc.

CMP: Planarization Technology, Slurry, Pad, Dress, End Point Detection, Cleaning, Anti-corrosive Technology, etc.

Contact: Silicide, Interface, Solid Phase Reaction, Shallow Junction, Crystal Properties, Electron Properties, Carrier Transport, Parasitic Resistance, etc.

MEMS/RF: Interconnection Structure and the materials, Packaging, Fabrication Process Technology, Device Design, etc.

Emerging Technology: Active Wiring, Power Electronics, Silicon Photonics, Flexible Electronics, Energy Harvesting, etc.

Backend Device Technology: Technology for Embedding Devices (MRAM, PCRAM, ReRAM, DRAM etc.), Materials and Process of Magnetics, Phase-Change and Resistive-Change Devices, Electrode, Metallization, etc.

Nanocarbon: Graphene, Carbon Nanotube, Deposition, Integration, Electrical Characteristics, Reliability, Evaluation, Analysis, etc.

3D and Packaging: TSV, TMV, Stacking Method (CoW, WoW), Thinning, Planarization, Bonding, Bump, Stress and Thermal Analysis, Sealing, Cooling, Reliability

★ **To Apply:** Prepare an abstract per the below directions and submit it to the ADMETA^{Plus} 2017 Secretariat **A4 format, 2 pages, Oral [15 min. talk & 5 min. QA] or Poster [90 min.] (temporary)**

★ **Abstract Preparation and Submission: Abstracts are due: June 30, 2017**

Prospective authors must submit a two-page PDF file with all figures and tables. Send the PDF file of the manuscript, the subject of your paper (please choose from the **Conference Topics of Interest**), and desired presentation style (Oral or Poster) to the secretariat office via e-mail. On the abstract, please indicate the author to whom correspondence should be addressed, and include mailing and e-mail addresses. A template of abstract can be downloaded from the ADMETA^{Plus} 2017 website. Notification of acceptance will be made to the authors by **August 14, 2017**. Upon notification, authors will be requested to confirm their participation in the conference.

The accepted abstracts will be included in the conference proceedings which the participants will receive on site at the registration desk of ADMETA^{Plus} 2017. Pre-registered participants will also be able to download the accepted abstracts from the ADMETA^{Plus} 2017 webpage after **Oct. 16, 2017**.

Authors with papers presented at ADMETA^{Plus} 2017 are encouraged to submit their original manuscripts to a Special Issue of the Japanese Journal of Applied Physics (JJAP) dedicated to the ADMETA^{Plus} 2017. The deadline for submission to the Special Issue is **November 20, 2017**. The manuscript will be reviewed based on the JJAP standard for an original paper. JJAP special issues are accepting regular papers (RP), brief notes (BN), and reviews (RV), and will be published in July, 2018.

✳️ **Reminder:** As the papers of the Special Issue will be the original papers, please be careful not to post the same contents to any other journals.

★ **Contact: ADMETA^{Plus} 2017 Secretariat**

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